L Number	Hits	Search Text	DB	Time stamp
17	2850	(solid near state) and (heat$4 WITH adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:53
24	229	((solid near state) and (heat$4 WITH adhesive)) and cross near linked	USPAT	2003/07/25 08:53
25	13	(solid near state with plate) and (heat$4 WITH adhesive) and cross near linked	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:56
32	1	(solid near state) and (heat$4 WITH adhesive with (cross near linked)) and (optical$5 near2 pump$4) and active	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:58
46	4	(solid near state) and (heat$4 WITH adhesive with (cross near linked))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:03
52	4	(solid near state) and (heat$4 WITH adhesive with (cross near linked)) and ((heat neat sink) or cool$5)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:06
39	5	(solid near state) and (heat$4 WITH adhesive with (cross near linked))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:22
58	2	(solid near state) and (adhesive with (cross near linked)) and active and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:26
65	12	(solid near state) and (adhesive with (cross near linked)) and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:40
72	0	(solid near state) and (adhesive near (layer or film or region or medium) with (cross near linked)) and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:36
79	29	(solid near state) and (adhesive near (layer or film or region or medium) with (cross near linked))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:48
86	0	(solid near state) and (adhesive with (cross near linked)) SAME (heat near sink)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:48
92	0	(solid near state) and (adhesive near (layer or film or region or medium) with (cross near linked)) and (optical$5 near pump$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:50

C:\APPS\east\workspaces\09921002.wsp

99	289	(solid near state) and (optical$5 near pump$4) and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:52
107	0	((solid near state) and (optical$5 near pump$4) and (heat near sink)) and (adhesive near (layer or film or region or medium) with (cross near linked))	USPAT	2003/07/25 09:54
108	0	((solid near state) and (optical$5 near pump$4) and (heat near sink)) and (adhesive with (cross near linked))	USPAT	2003/07/25 09:54
106	238	(solid near state) and (optical$5 near pump$4) and (heat near sink)	USPAT	2003/07/25 10:01
109	209	((solid near state) and (optical$5 near pump$4) and (heat near sink)) and 372/$.ccls.	USPAT	2003/07/25 09:59
110	190	(solid near state near laser) and (optical$5 near pump$4) and (heat near sink) and 372/$.ccls.	USPAT	2003/07/25 10:21
111	81	(solid near state near laser) and (optical$5 near pump$4) and (heat near sink) and 372/$.ccls. and amplif$5	USPAT	2003/07/25 10:23
-	1002	(solid near state) and active and amplif$5 and cool$4 and thermal$5 and heat$4 and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 16:54
-	391	(solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 16:59
-	251	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and 372/$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 17:01
-	259	(solid near state near laser) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 17:01
-	199	((solid near state near laser) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and 372/$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:00
-	154	((solid near state near laser) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and liquid and solid and material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:03
-	244	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and liquid and solid and material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:29
-	162	(((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and liquid and solid and material) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:24

C:\APPS\east\workspaces\09921002.wsp

		47	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 same heat$4) and (liquid with solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:35
-		55	((solid near state) and active and (laser with amplif$5) and cool$4 and thermal$5 and heat$4) and (liquid with solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:40
-		113	(solid near state) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid same solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:44
-		84	((solid near state) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid same solid same material)) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:17
-		1	((solid near state with plate) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid same solid same material)) and volum$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:23
-		8	(((solid near state) with plate) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:26
-		20	((solid near state) with plate) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:33
-		20	(((solid near state) SAME plate) and semiconductor and active and laser and amplif$5 and cool$4 and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:36
-		1	(((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif$5) and (cool$4 near2 (body or member or system)) and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:45
-		2	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif$5) and (cool$4 near2 (body or member or system)) and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:50
-		1	(((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif$5) and (cool$4 near2 (body or member or system)) and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:54

-		1	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif$5) and cool$5 and (thermal$5 near2 (body or member or system)) and heat$4 and (liquid AND solid AND material)) and volum$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:58
-		0	(((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif$5) and cool$5 and (thermal$5 near2 (body or member or system)) and heat$4 and (liquid AND solid AND material)) and volum$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:02
-		1	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif$5) and cool$5 and (thermal$5 near2 (body or member or system)) and heat$4 and (liquid AND solid AND material)) and volum$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:06
-		95	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif$5) and (cool$5) and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-		2	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif$5) and (cool$5 near2 (body or member or system)) and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-		8	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif$5) and (cool$5 near2 (body or member or system)) and thermal$5 and heat$4 and (liquid AND solid AND material)) and volum$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-		22	(solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif$5) and (cool$5 near2 (body or member or system)) and heat$4 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:27
-		20	(solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif$5) and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:46
-		15	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif$5) and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5) and (mirror or reflect$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:40
-		40	(solid near state) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (mirror or reflect$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 17:06
-		8	((solid near state) and (active near (layer or region or medium or film)) and laser and (cool$5 near2 (body or member or system)) and heat$4 and plate and thermal$5 and (mirror or reflect$5)) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:49